

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
262-253-5900 FAX 262-253-5919

DESCRIPTION:

ResinLab® Armstrong™ C-4 with Activator A is a two-part clear low viscosity room temperature curing epoxy adhesive. It was designed for bonding glass, ceramics, most metals, and many plastics. Once cured it will produce a clear rigid bond line. *Armstrong™ C-4 with Activator A* is well suited for fiber optic bonding applications as well as other electronic and aerospace applications. It will have excellent chemical and solvent resistance as well as electrical insulation properties.

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TYPICAL PROPERTIES:

All properties given are at 25 °C unless otherwise noted.

Property:	Value:	Test Method or Source:
Color	Transparent Clear	Visual
Mix Ratio	Part A to Part B	Calculated
Mix Ratio by weight	9.1 to 1	Extrapolated from Henkel LDS
Mix Ratio by volume	7.8 to 1	
Cure Schedule	24 hrs @ 25 °C 4 hrs @ 65 °C	Extrapolated from Henkel LDS
Viscosity - Part A	795 cP	TA HR20 Rheometer 25mm parallel plate @
Viscosity - Part B	30 cP	1/s DCV6100723
Viscosity - Mixed	300 cP	
Specific Gravity - Part A	1.13	Calculated
Specific Gravity - Part B	0.95	
Specific Gravity - Mixed	1.11	
Pot Life defined as the time it takes for initial mixed viscosity to double	1.5 hours	TA HR20 Rheometer parallel plate 25mm @ 1/s DCV6100723
Hardness	80 Shore D	455300006287/ASTM D2240
Glass Transition Temperature/Tg	77 °C	Extrapolated from Henkel LDS
AC Dielectric Strength	20 kV/mm	Extrapolated from Henkel LDS
Dielectric Constant / Dissipation Factor @ 1 kHz	4.3 / 0.02	Extrapolated from Henkel LDS
Operating Temperature Range	-60 to 130 °C**	
Relative Thermal Index (RTI)	90 °C	UL746B, Table 7.1 Generic Value Based on Composition

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.

** Operating Temperature Range is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.

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*** This TDS contains values that have been updated. The values reported in this technical data sheet are typical values of the product, and are highly dependent on test conditions and methodology. We actively seek the most precise and accurate ways to measure and interpret performance of our products, and to update estimated values with measured values. The formula has not been revised or changed in any way. Although the values on paper have changed, you can expect the same performance of the product.

INSTRUCTIONS:

1. Bring to room temperature prior to use.
2. Bulk format: stir until homogeneous weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on the surface of the casting. Maintain adequate velocity during dispensing to ensure complete mixing.
3. Clean up uncured resin with suitable organic solvent such as MEK or acetone.
4. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.

SHELF LIFE AND STORAGE:

12 months at 25 °C.
Specialty packaging may be less.

Many epoxy resin systems are prone to crystallization as epoxy resin is a super-cooled fluid. This condition may give the product a gritty or grainy appearance (or hazy in clear products). Products in this state will not usually cure to normal and expected properties. In extreme cases it may appear solid and cured. Fluctuating temperatures (within 5 to 50 °C) aggravate this phenomenon. Heating the individual component to 50 to 60 °C while stirring can usually restore products to original state. Storage at 25 +/- 10 °C is optimum for most products.